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OTSUBO et al.(10) **Pub. No.: US 2023/0230951 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **CIRCUIT MODULE****H01L 23/552** (2006.01)**H01L 23/66** (2006.01)**H01L 23/538** (2006.01)(71) Applicant: **Murata Manufacturing Co., Ltd.**,
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ABSTRACT

To provide a circuit module capable of suppressing a decrease in an area for mounting an electronic component on a substrate even when a wire for shielding the electronic component is connected to the substrate. A circuit module according to the present disclosure includes a substrate, a first component mounted on the substrate and including a ground terminal on an upper surface, first wires that connect the ground terminal to the substrate, and a second component mounted on the substrate, in which overlapping first wires in plan view.

